

8. (Amended) The probe card according to claim 6,  
wherein the resultant conductor circuits formed through said resin layer are  
interconnected to each other by a via hole.
9. (Amended) The probe card according to claim 6,  
wherein said ceramic board comprises non-oxide ceramic.
10. (Amended) The probe card according to claim 6,  
wherein said resin layer comprises thermosetting resin.
11. (Amended) The probe card according to claim 6,  
wherein said ceramic board is in a disc shape.
12. (Amended) The probe card according to claim 6,  
wherein said resin layer is formed so as to cover the whole of at least one of main  
faces of said ceramic board.

Please add new Claims 13-19 as follows:

13. (New) The inspecting device according to claim 2,  
wherein the ceramic board of said probe card comprises non-oxide ceramic.
14. (New) The inspecting device according to claim 3,  
wherein the ceramic board of said probe card comprises non-oxide ceramic.
15. (New) The inspecting device according to claim 2,  
wherein said resin thin film comprises thermosetting resin.
16. (New) The inspecting device according to claim 3,  
wherein said resin thin film comprises thermosetting resin.
17. (New) The inspecting device according to claim 4,  
wherein said resin thin film comprises thermosetting resin.